



Material Content Data Sheet



Sales Product Name	TLE75602-ESD			Issued	4. March 2019			
MA#	MA001709394							
Package	PG-TSDSO-24-21			Weight*	112.09 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.094	2.76	2.76	27600	27600
leadframe	inorganic material	phosphorus	7723-14-0	0.016	0.01		141	
	non noble metal	zinc	7440-66-6	0.063	0.06		565	
	non noble metal	iron	7439-89-6	1.266	1.13		11292	
wire	non noble metal	copper	7440-50-8	51.392	45.85	47.05	458501	470499
	non noble metal	copper	7440-50-8	0.939	0.84	0.84	8375	8375
	organic material	carbon black	1333-86-4	0.150	0.13		1342	
encapsulation	plastics	epoxy resin	-	5.865	5.23		52328	
	inorganic material	silicondioxide	60676-86-0	44.114	39.36	44.72	393576	447246
leadfinish	non noble metal	tin	7440-31-5	2.820	2.52	2.52	25160	25160
plating	noble metal	silver	7440-22-4	1.279	1.14	1.14	11411	11411
glue	plastics	epoxy resin	-	0.190	0.17		1699	
	noble metal	silver	7440-22-4	0.898	0.80	0.97	8010	9709
*deviation	< 10%			Sum in total:		100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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